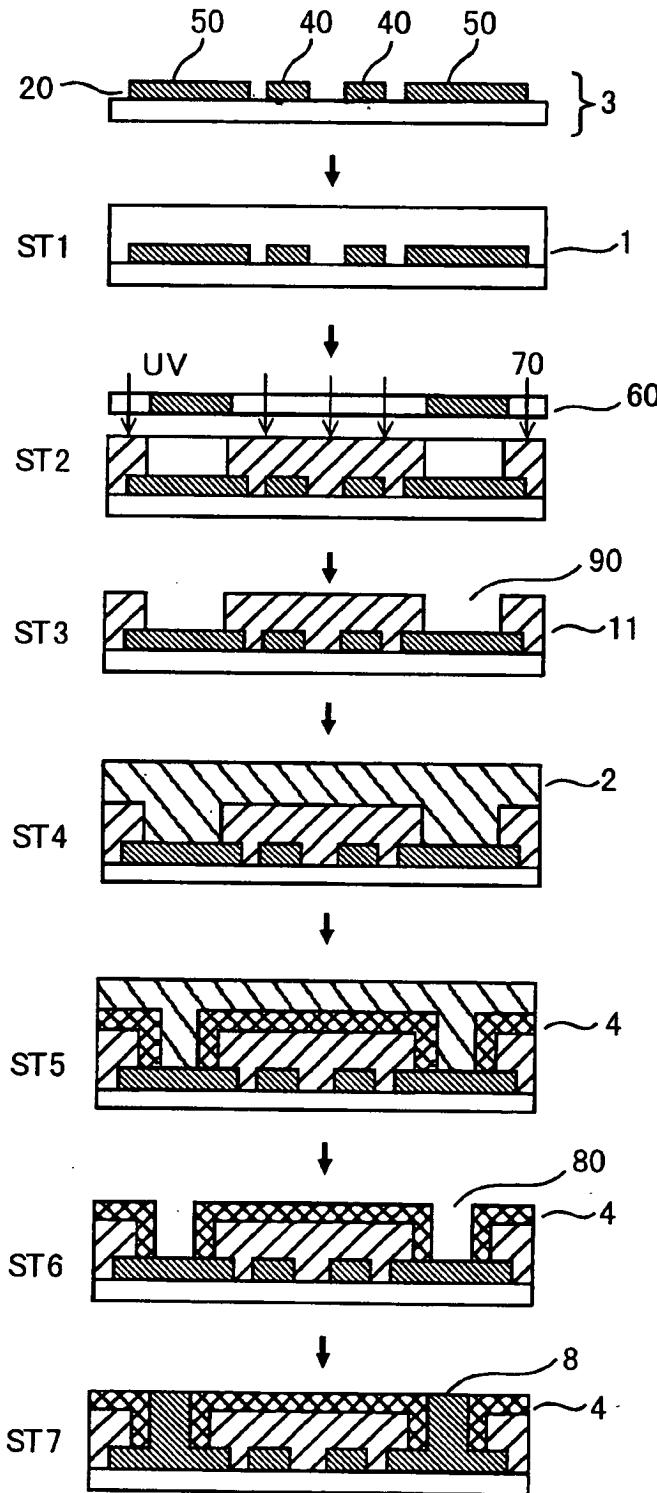


Fig. 1



000233855424800

Fig.2

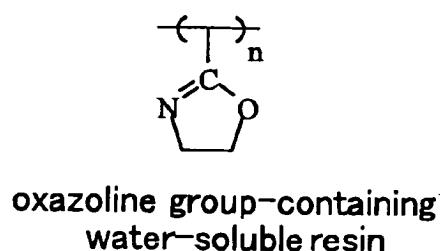
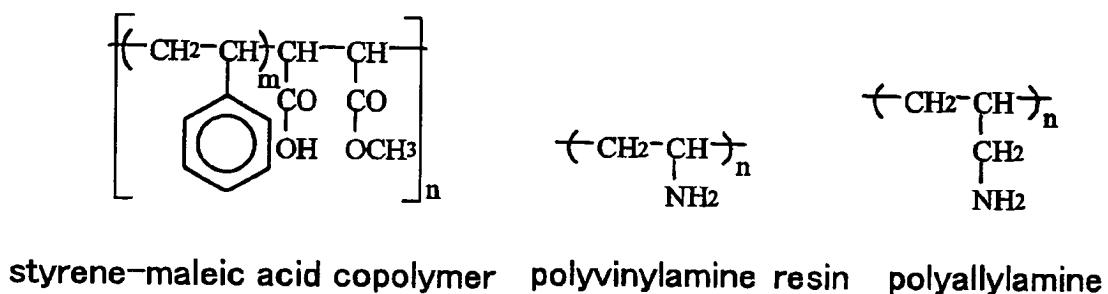
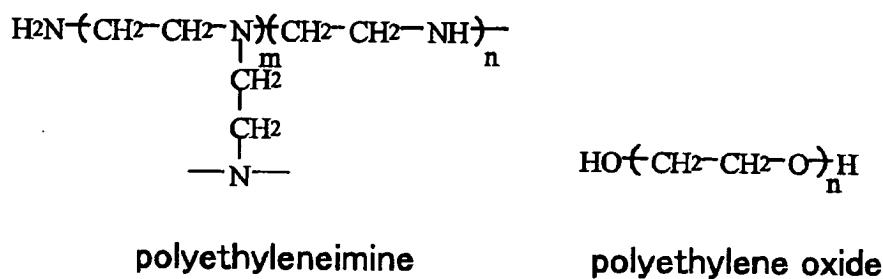
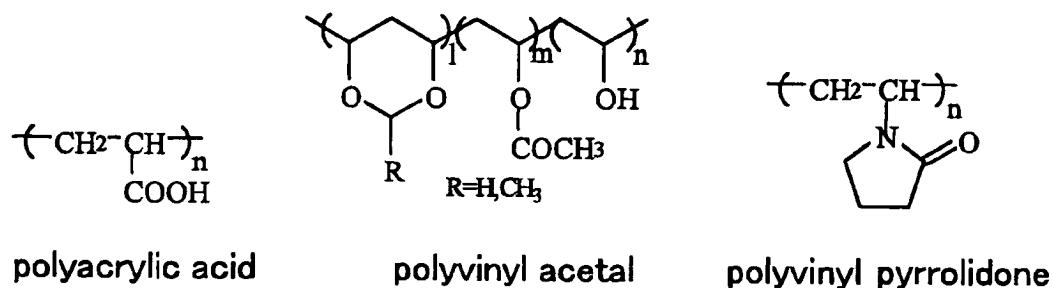
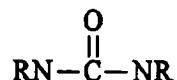
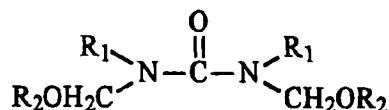
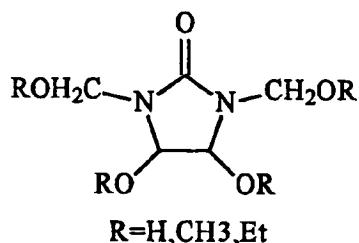


Fig.3



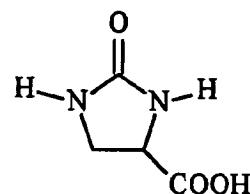
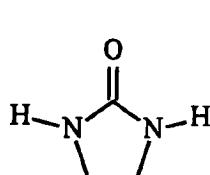
R=H,CH₃,CH₂OMe,CH₂OEt

ureaderivatives



R1=H,CH₃,CH₂OMe,CH₂OEt
 R2=H,CH₃,Et

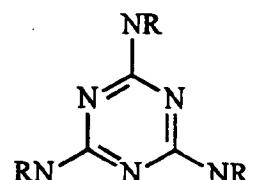
alkoxymethylurea



N-alkoxyethyleneurea

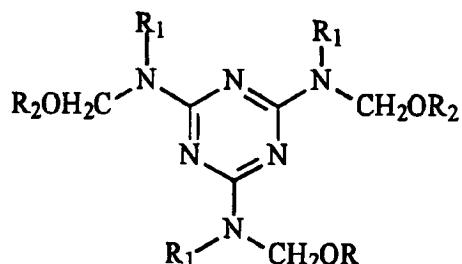
ethyleneurea

ethyleneureacarboxylic acid



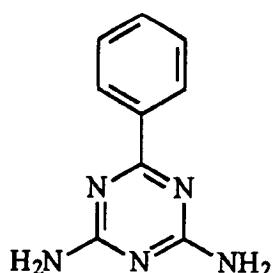
R=H,CH₃,CH₂OMe,CH₂OEt

melamine derivatives

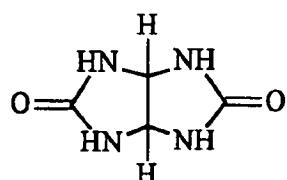


R1=H,CH₃,CH₂OMe,CHOEt
 R2=H,CH₃

alkoxymethylmelamine derivatives



benzoguanamine



glycoluril

Fig.4

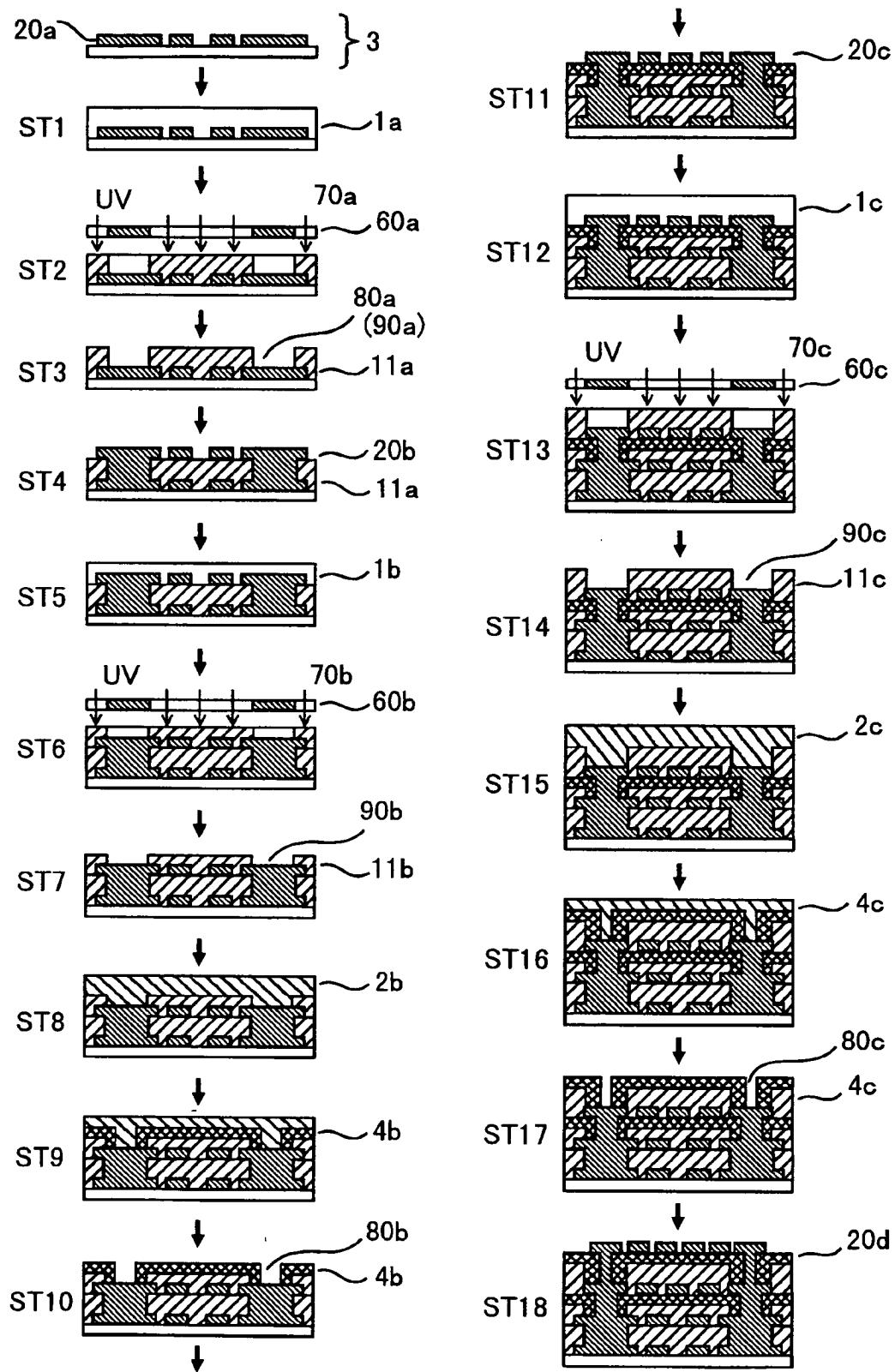
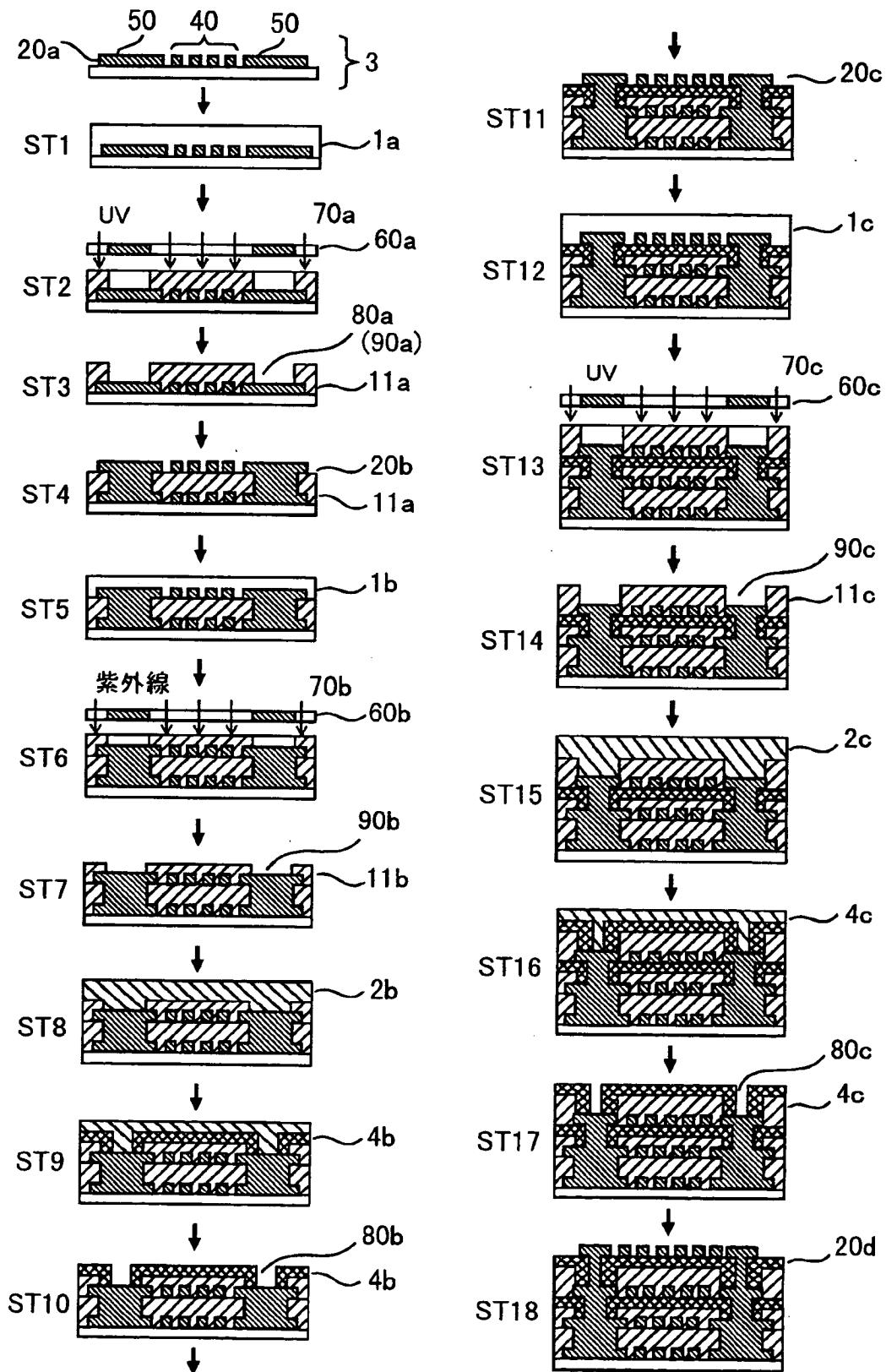
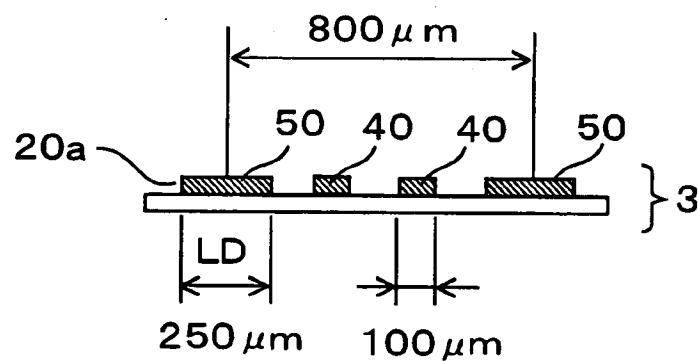


Fig.5



007493856250

Fig.6

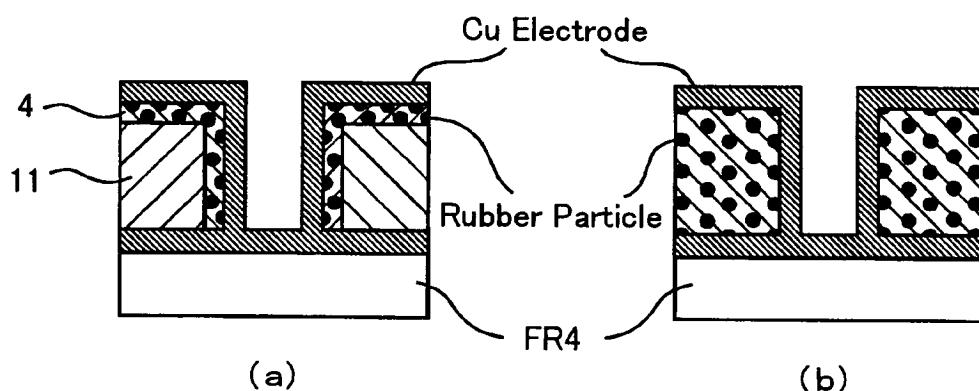


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Fig.7

Evaluation Board A

Evaluation Board B



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Fig.8 PRIOR ART

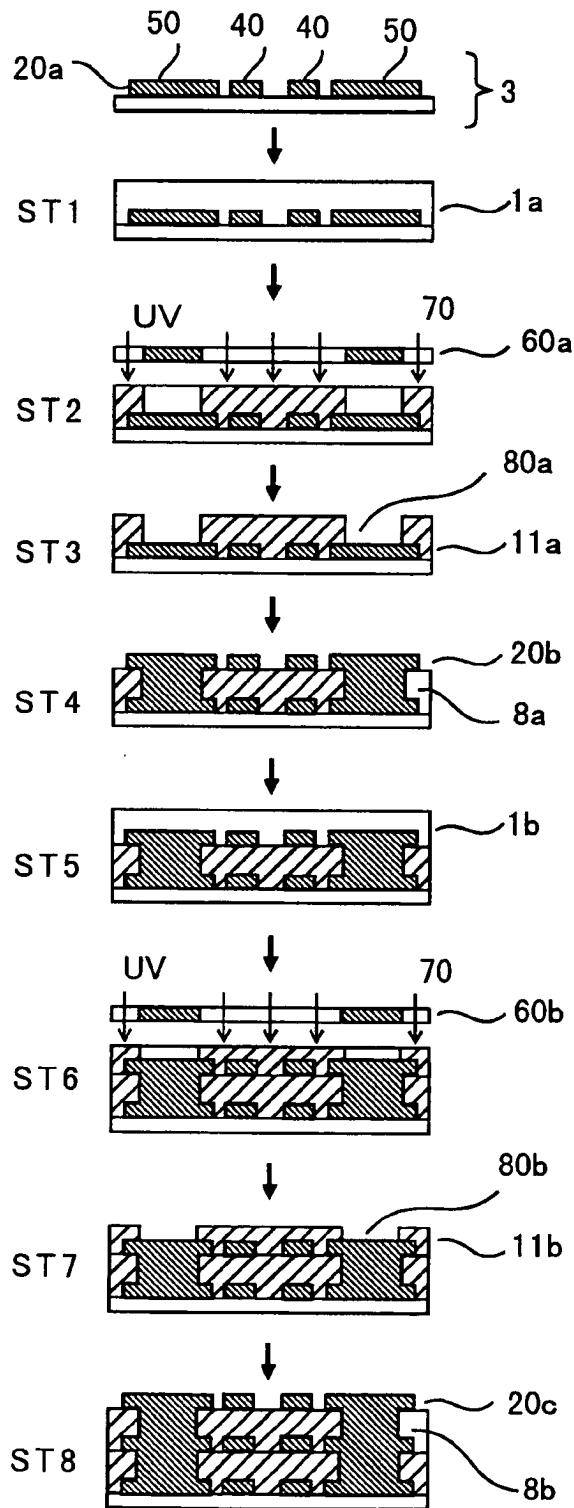


Table 1

Condition	Diameter of Via-Hole
Non Heat Treatment	150 μm
120°C/60min	130 μm
130°C/30min	100 μm
140°C/30min	70 μm

Table 2

Condition	Diameter of Via-Hole
Non Heat Treatment	150 μm
110°C/10min	120 μm
110°C/20min	100 μm
110°C/30min	80 μm
135°C/40min	40 μm

Table 3

Condition	Diameter of Via-Hole
Non Heat Treatment	150 μm
110°C/15min	120 μm
120°C/15min	100 μm
130°C/15min	80 μm
135°C/20min	45 μm

Table 4

Condition	Diameter of Via-Hole
Non Heat Treatment	100 μm
120°C/30min	96 μm
130°C/30min	90 μm
140°C/30min	83 μm

Table 5

Sample	Dielectric Constant [1kHz] 25°C	Thermal Expansion [Vertical] 80~120°C	Peel Strength [90° Peel] 25°C
Evaluation Board A	4.5	40ppm	980kg/cm
Evaluation Board B	4.8	55ppm	970kg/cm